

Lithographically Patterned Metallic Conduction in Single-Layer MoS₂ via Plasma Processing

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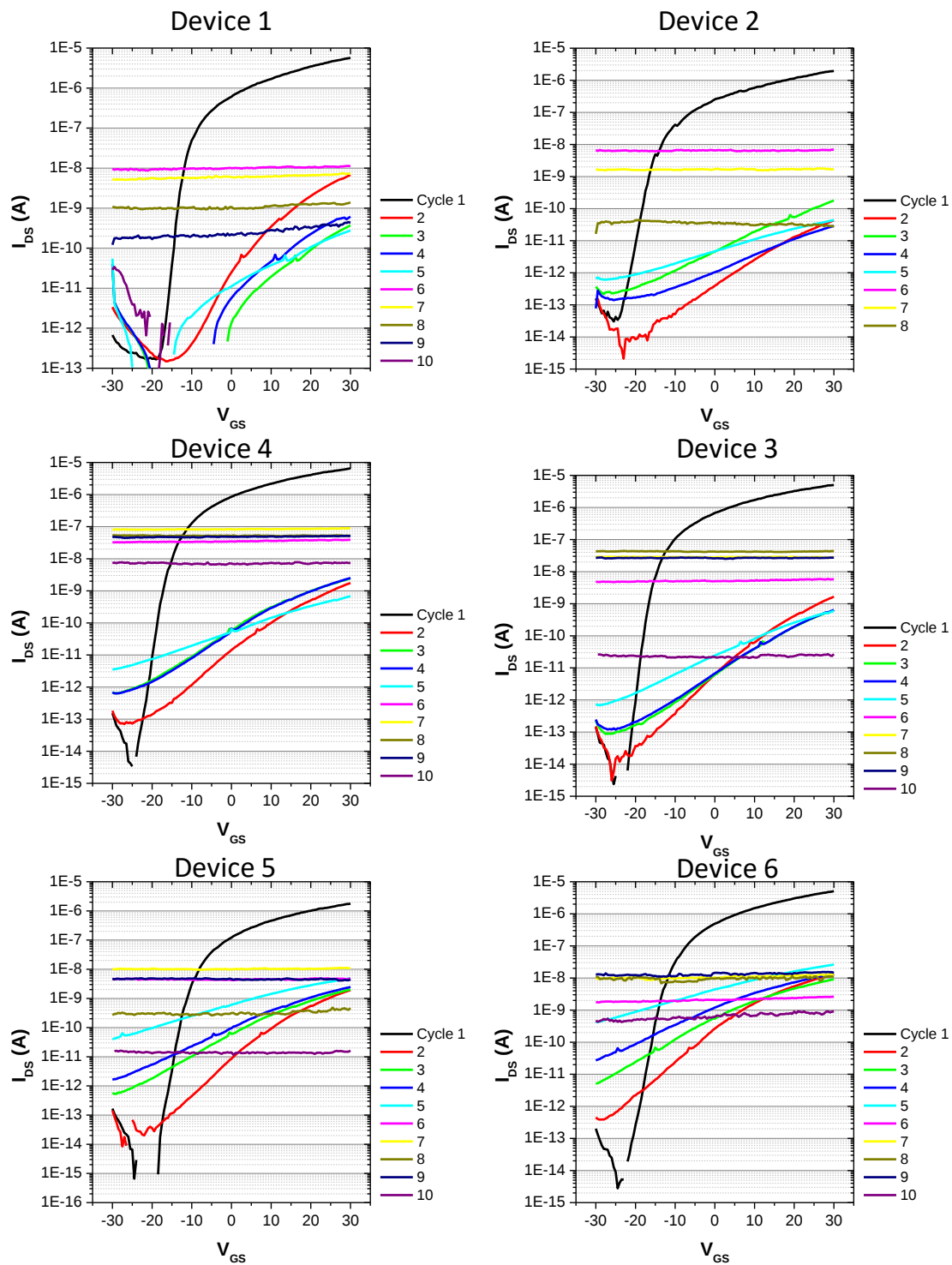


Figure S1. Transfer curves for 6 MoS₂ field-effect transistors exposed to cycles of hydrogen plasma and atmospheric oxygen.

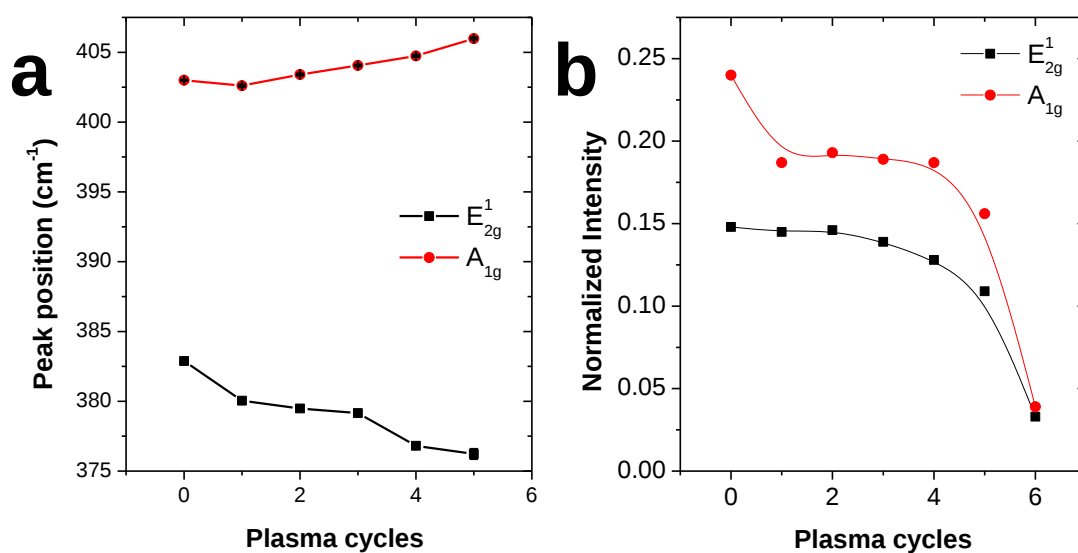


Figure S2. (a) Position of MoS₂ E_{2g}¹ and A_{1g} Raman peaks as a function of plasma cycles.
(b) Intensity of the respective Raman peaks as a function of plasma cycles.

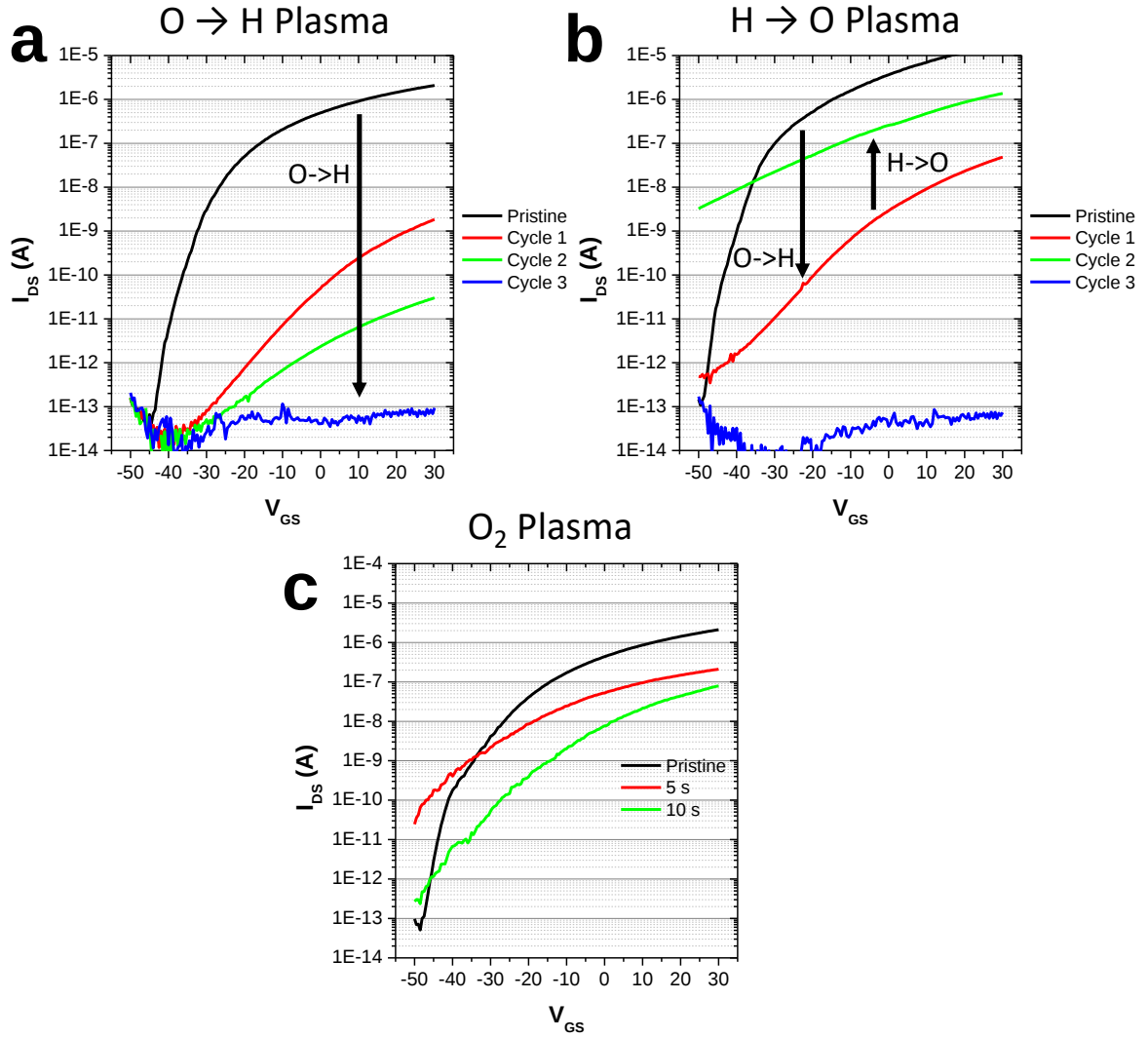


Figure S3. Transfer curves for MoS₂ FETs after exposed to various strategies of plasma exposure. (a) Transfer curves when exposed to cycles of O plasma followed by H plasma ($O \rightarrow H$ plasma). This results in insulating behavior for the material. (b) Transfer curve for a device in which the first plasma cycle was $O \rightarrow H$ plasma. This, once again, resulted in a suppression in conductivity over all gate voltages. A subsequent $H \rightarrow O$ plasma was employed which increased the conductivity of the MoS₂. (c) Transfer curves for a device which was solely exposed to O plasma.

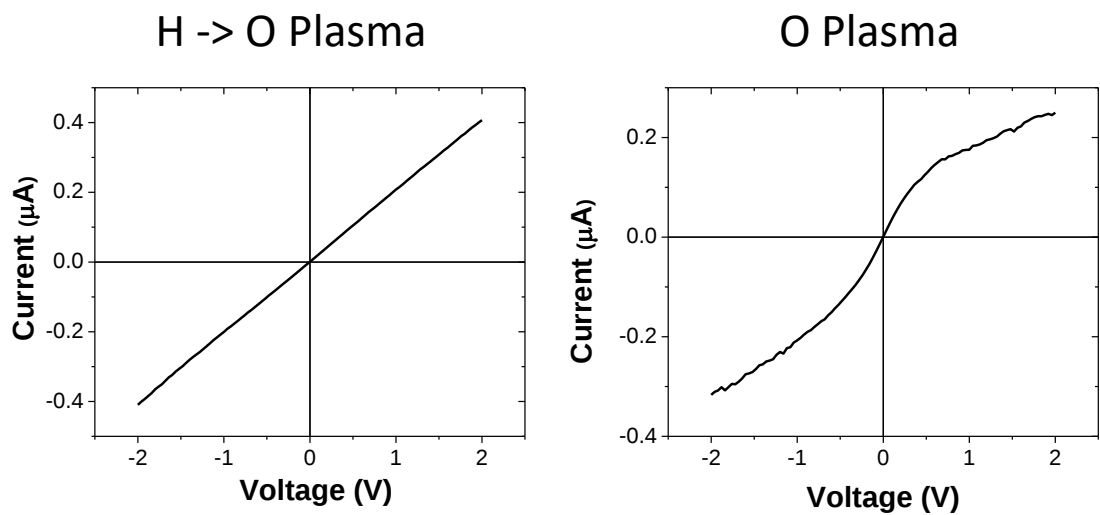


Figure S4. Current-voltage (I-V) characteristics for MoS₂ FETs exposed to H $\rightarrow$ O plasma cycles (left) and solely oxygen plasma (right). Linear I-V characteristics for the H $\rightarrow$ O plasma cycles suggest that the material exhibits metallic conduction.

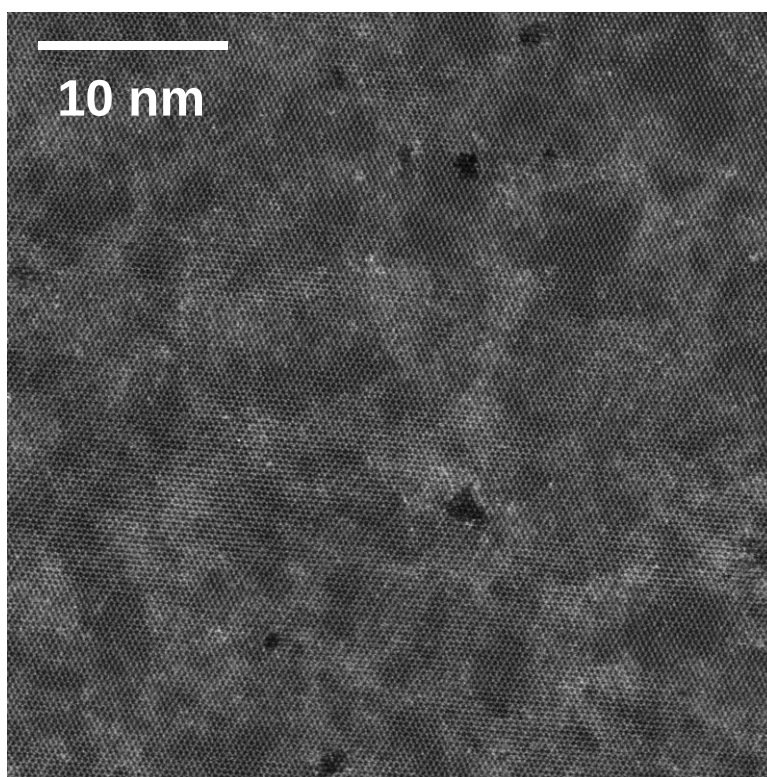


Figure S5. STEM image showing MoS₂ exposed to H₂ + 2s O₂ plasma exposure.

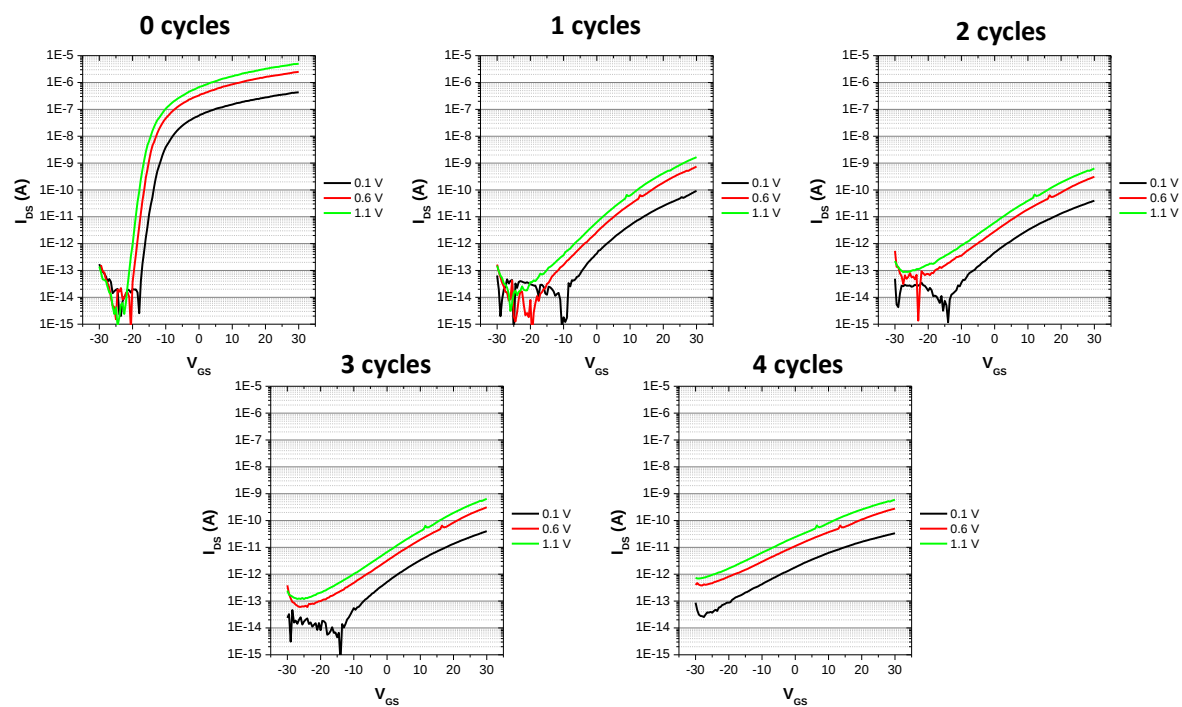


Figure S6. Transfer curves for MoS₂ after H₂ plasma + atmosphere cycles. Notably, DIBL increases with increasing plasma cycles. Devices are no longer able to turn “off” at 1.1 V source-drain voltage after 2 cycles of plasma.